



- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

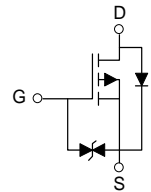
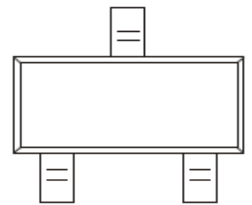
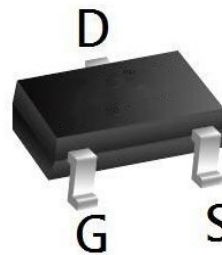
Product Summary

BVDSS	RDSON	ID
-20V	500mΩ	-0.66A

Description

The XXW3139 is the high cell density trenched P-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications. The XXW3139 meet the RoHS and Green Product requirement with full function reliability approved.

ESD Rating: 2000V HBM

SOT523 Pin Configuration

Maximum ratings (T_a=25°C unless otherwise noted)

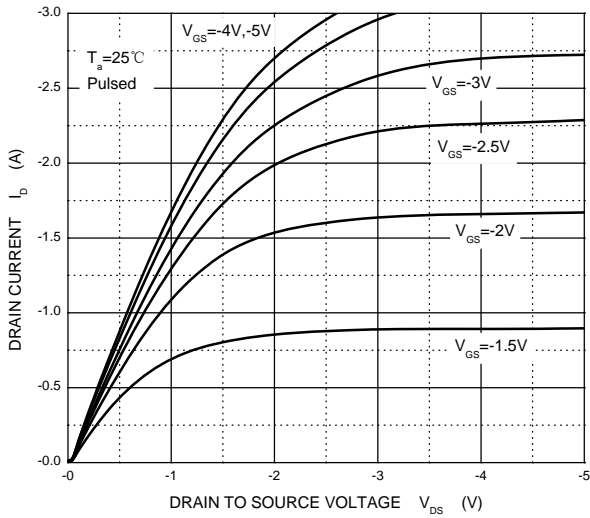
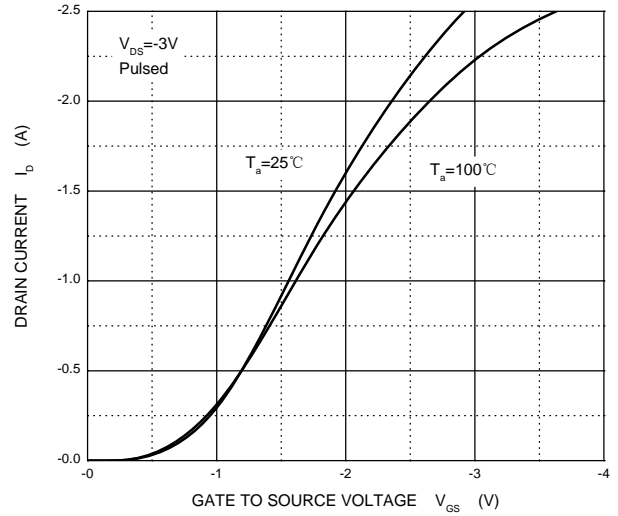
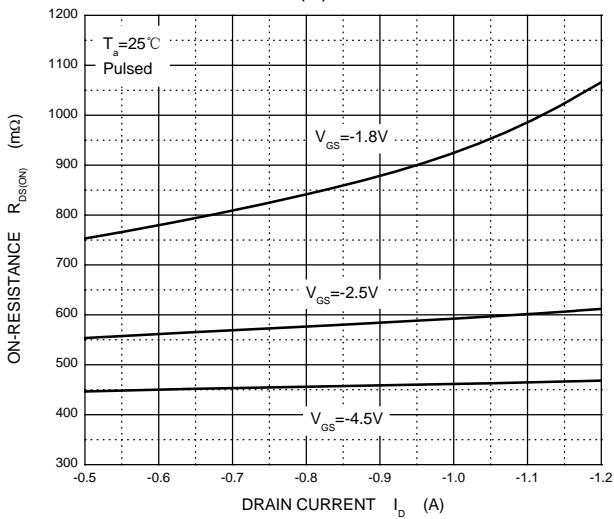
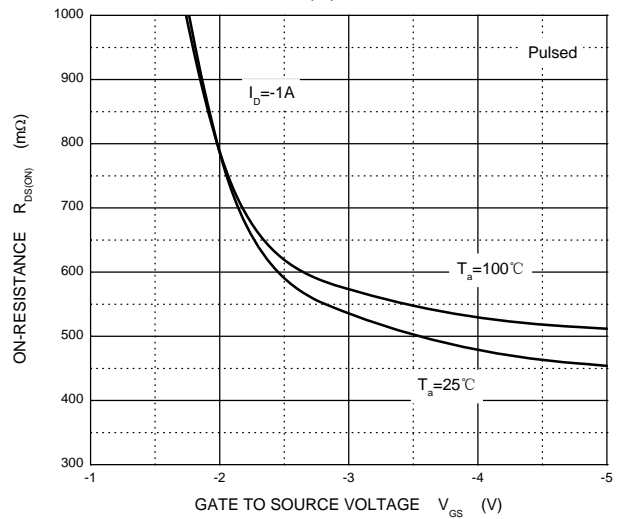
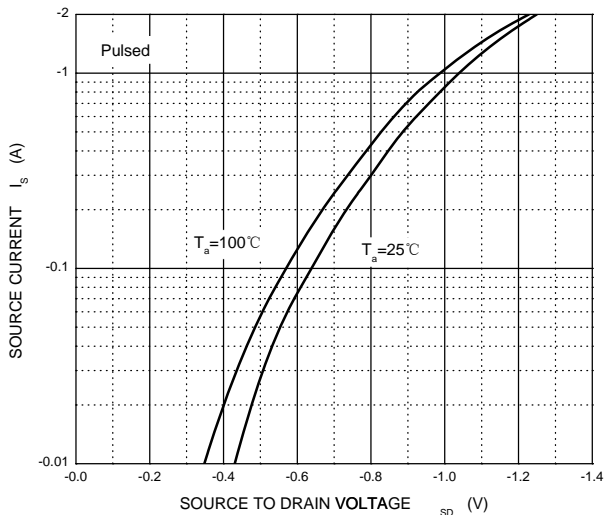
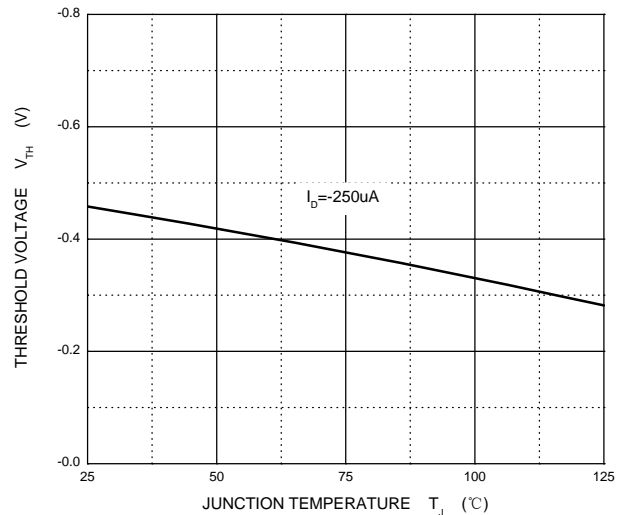
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-20	V
Typical Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current (note 1)	I _D	-0.66	A
Pulsed Drain Current (t _p =10 μs)	I _{DM}	-1.2	A
Power Dissipation (note 1)	P _D	150	mW
Thermal Resistance from Junction to Ambient (note 1)	R _{θJA}	833	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T _L	260	°C

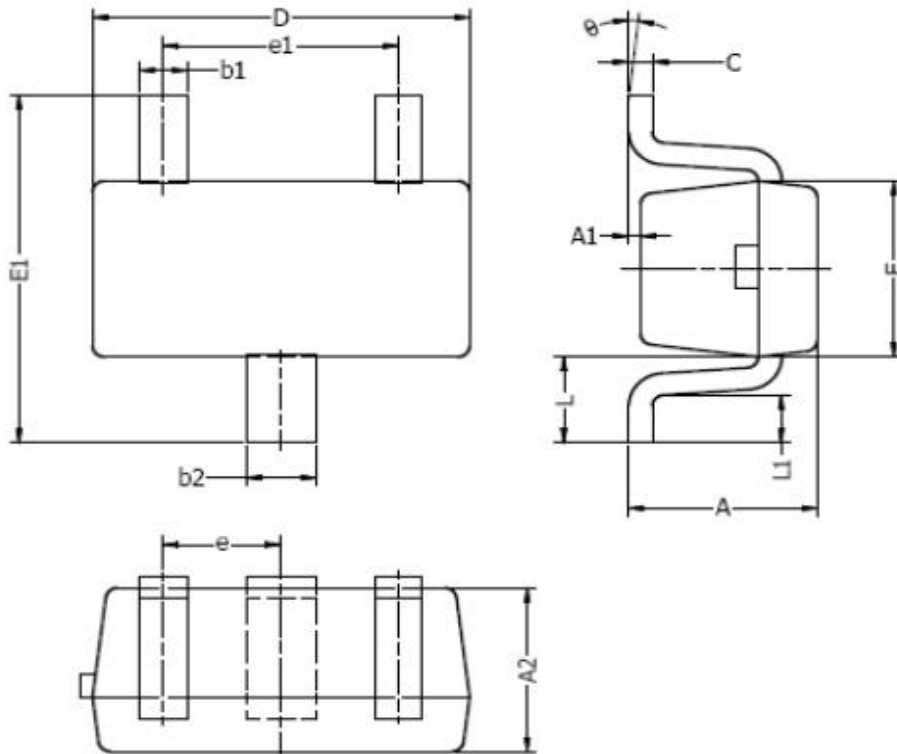
T_a=25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±10V, V _{DS} = 0V			±20	μA
Gate threshold voltage (note 2)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.35		-1.1	V
Drain-source on-resistance (note 2)	R _{DS(on)}	V _{GS} = -4.5V, I _D = -1A			520	mΩ
		V _{GS} = -2.5V, I _D = -0.8A			700	mΩ
		V _{GS} = -1.8V, I _D = -0.5A		950		mΩ
Forward transconductance (note 2)	g _{FS}	V _{DS} = -10V, I _D = -0.54A		1.2		S
Diode forward voltage	V _{SD}	I _S = -0.5A, V _{GS} = 0V			-1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input capacitance	C _{iss}	V _{DS} = -16V, V _{GS} = 0V, f = 1MHz		113	170	pF
Output capacitance	C _{oss}			15	25	pF
Reverse transfer capacitance	C _{rss}			9	15	pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time (note 3)	t _{d(on)}	V _{GS} = -4.5V, V _{DS} = -10V, I _D = -200mA, R _{GEN} = 10Ω		9		ns
Turn-on rise time (note 3)	t _r			5.8		ns
Turn-off delay time (note 3)	t _{d(off)}			32.7		ns
Turn-off fall time (note 3)	t _f			20.3		ns

Notes :

1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse Width=300μs, Duty Cycle=2%.
3. Switching characteristics are independent of operating junction temperatures.
4. Guaranteed by design, not subject to producing.

Typical Characteristics
Output Characteristics

Transfer Characteristics

 $R_{DS(ON)}$ — I_D

 $R_{DS(ON)}$ — V_{GS}

 I_S — V_{SD}

Threshold Voltage


Package Mechanical Data-SOT-523


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.10	0.000	0.004
A2	0.70	0.80	0.028	0.031
b1	0.15	0.25	0.006	0.010
b2	0.25	0.35	0.010	0.014
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
E1	1.45	1.75	0.057	0.069
e	0.50 TYP.		0.020 TYP.	
e1	0.90	1.10	0.035	0.043
L	0.40 REF.		0.016 REF.	
L1	0.10	0.30	0.004	0.012
θ	0°	8°	0°	8°

NOTES:

1. Above package outline conforms to JEITA EAJ ED-7500A SC-75A.
2. Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.